

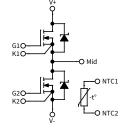
1700 V, 380 A, Silicon Carbide, Half-Bridge Module

$V_{ extsf{DS}}$	1700 V
I _{DS}	380 A

Technical Features

- Ultra-Low Loss, High Frequency Operation
- Zero Turn-Off Tail Current from MOSFET
- Normally-Off, Fail-Safe Device Operation
- Anti-Parallel Schottky Diode
- Temperature-Independent Switching Behavior





Typical Applications

- Railway, Traction, and Motor Drives
- EV Chargers
- High-Efficiency Converters/Inverters
- Renewable Energy
- Smart-Grid/Grid-Tied Distributed Generation

System Benefits

- Enables Compact, Lightweight Systems
- Increased System Efficiency, due to Low Switching & Conduction Losses of SiC
- Reduced Thermal Requirements and System Cost

Key Parameters

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	Note	
Drain-Source Voltage	V _{DS}			1700		T _c = 25 °C		
Gate-Source Voltage, Maximum Value	V _{GS(max)}	-8		+19	V	Transient	Note 1	
Gate-Source Voltage, Recommended	$V_{GS(op)}$		-4/+15			Static	Fig. 33	
			532			$V_{GS} = 15 \text{ V}, T_C = 25 \text{ °C}, T_{VJ} \le 175 \text{ °C}$		
DC Continuous Drain Current	l _D	I _D		406			$V_{GS} = 15 \text{ V}, T_C = 90 \text{ °C}, T_{VJ} \le 175 \text{ °C}$	Notes
DC Source-Drain Current (Schottky Diode)	I _{SD(SD)}		531		А	$V_{GS} = -4 \text{ V}, T_C = 25 \text{ °C}, T_{VJ} \le 175 \text{ °C}$	2, 3 Fig. 21	
Pulsed Drain-Source Current	I _{DM}		760			t_{Pmax} limited by T_{VJmax} $V_{GS} = 15 \text{ V}, \ T_C = 25 ^{\circ}\text{C}$		
Power Dissipation	P _D		1899		W	T _C = 25 °C, T _{VJ} ≤ 175 °C	Note 4 Fig. 21	
Virtual Junction Temperature	T _{VJ(op)}	-40		175	°C			

Note (1): Recommended turn-on gate voltage is 15 V with ±5 % regulation tolerance

Note (2): Current limit calculated by $I_{D(max)} = \sqrt{(P_D/R_{DS(typ)}(T_{VJ(max)},I_{D(max)}))}$

Note (3): Verified by design

Note (4): $P_D = (T_{VJ} - T_C)/R_{TH(JC,typ)}$

MOSFET Characteristics (Per Position) (T_{VJ} = 25 °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	Note
Drain-Source Breakdown Voltage	V _{(BR)DSS}	1700				V _{GS} = 0 V, T _{VJ} = -40 °C	
Cata Thurshald Waltana	.,,	1.8	2.5	3.6	V	$V_{DS} = V_{GS}, I_D = 152 \text{ mA}$	
Gate Threshold Voltage	$V_{GS(th)}$		2.0			$V_{DS} = V_{GS}$, $I_D = 152$ mA, $T_{VJ} = 175$ °C	
Zero Gate Voltage Drain Current	I _{DSS}		14		μΑ	V _{GS} = 0 V, V _{DS} = 1700 V	
Gate-Source Leakage Current	I _{GSS}		6		nA	V _{GS} = 15 V, V _{DS} = 0 V	
Drain-Source On-State Resistance			2.86	3.74		V _{GS} = 15 V, I _D = 380 A	Fig. 2
(Devices Only)	R _{DS(on)}		6.49		mΩ	V _{GS} = 15 V, I _D = 380 A, T _{VJ} = 175 °C	Fig. 3
			322			V _{DS} = 20 V, I _D = 380 A	Fig. 4
Transconductance	g fs		308		S	V _{DS} = 20 V, I _D = 380 A, T _{VJ} = 175 °C	
Turn-On Switching Energy, $T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 125 ^{\circ}\text{C}$ $T_{VJ} = 175 ^{\circ}\text{C}$	E _{on}		8.6 8.6 8.6			$\begin{split} &V_{DD} = 900 \text{ V} \\ &I_{D} = 380 \text{ A}, \\ &V_{GS} = -4 \text{ V}/15 \text{ V}, \\ &R_{G(OFF)} = 0.0 \Omega, R_{G(ON)} = 0.0 \Omega, \\ &L = 14 \mu\text{H} \end{split}$	Fig. 11 Fig. 13
Turn-Off Switching Energy, $T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 125 ^{\circ}\text{C}$ $T_{VJ} = 175 ^{\circ}\text{C}$	E _{OFF}		4.3 4.8 5.0		mJ		
Internal Gate Resistance	R _{G(int)}		1.23		Ω	f = 100 kHz	
Input Capacitance	C _{iss}		47		_		
Output Capacitance	Coss		2.6		nF	$V_{GS} = 0 \text{ V, } V_{DS} = 1200 \text{ V}$ $V_{AC} = 25 \text{ mV, } f = 100 \text{ kHz}$	Fig. 9
Reverse Transfer Capacitance	C _{rss}		31		pF		
Gate to Source Charge	Q _{GS}		480			V_{DS} = 1200 V, V_{GS} = -4 V/15 V I_D = 550 A Per IEC60747-8-4 pg 21	
Gate to Drain Charge	Q_{GD}		420		nC		
Total Gate Charge	Q _G		1494				
FET Thermal Resistance, Junction to Case	R _{th JC}		0.079		°C/W		Fig. 17

Diode Characteristics (Per Position) (T_{VJ} = 25 °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	Note
5: 1.5	.,,		1.6		V	$V_{GS} = -4 \text{ V}, I_{SD} = 380 \text{ A}$	Fig. 7
Diode Forward Voltage	V _{SD}		2.5			V _{GS} = -4 V, I _{SD} = 380 A, T _{VJ} = 175 °C	
Reverse Recovery Time	t _{RR}		24		ns		
Reverse Recovery Charge	Q _{RR}		4.8		μС	$V_{GS} = -4 \text{ V}, I_{SD} = 380 \text{ A}, V_{R} = 900 \text{ V}$ $di/dt = 27 \text{ A/ns}, T_{VJ} = 175 \text{ °C}$	Fig. 32
Peak Reverse Recovery Current	I _{RRM}		330		А		
Reverse Recovery Energy, $T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 125 ^{\circ}\text{C}$ $T_{VJ} = 175 ^{\circ}\text{C}$	E _{RR}		2.2 2.2 2.2		mJ	$V_{DD} = 900 \text{ V}, I_D = 380 \text{ A},$ $V_{GS} = -4 \text{ V}/15 \text{ V}, R_{G(ext)} = 0.0 \Omega,$ $L = 14 \mu H$	Fig. 14 Note 5
Diode Thermal Resistance, Junction to Case	R _{th JC}		0.091		°C/W		Fig. 18

Note (5): SiC Schottky diodes do not have reverse recovery energy but still contribute capacitive energy.

Module Physical Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Package Resistance, M1 (High-Side)	R ₁₋₂		106.5			T _c = 125 °C, Note 6
Package Resistance, M2 (Low-Side)	R ₂₋₃		126.3		μΩ	T _c = 125 °C, Note 6
Stray Inductance	L _{Stray}		4.9		nH	Between DC- and DC+, f = 10 MHz
Case Temperature	T _C	-40		125	°C	
Mounting Torque		3	4.5	5	N-m	Baseplate, M6 Bolts
	Ms	0.9	1.1	1.3		Power Terminals, M4 Bolts
Weight	W		167		g	
Case Isolation Voltage	V _{isol}	4			kV	AC, 50 Hz, 1 minute
Comparative Tracking Index	СТІ	600				
Cl. D'. I		13.07				Terminal to Terminal
Clearance Distance		6.00				Terminal to Heatsink
Creepage Distance		14.27			mm	Terminal to Terminal
		12.34				Terminal to Heatsink

Note (6): Total Effective Resistance (Per Switch Position) = MOSFET R_{DS(on)} + Switch Position Package Resistance

NTC Characteristics (T_{NTC} = 25 °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Notes
Resistance at 25 °C	R ₂₅		4700		Ω	
Tolerance of R ₂₅			±1		%	
Beta Value for 25 °C to 85 °C	B _{25/85}		3435		К	
Beta Value for 0 °C to 100 °C	B _{0/100}		3399		K	
Tolerance of B _{25/85}			±1		%	
Maximum Power Dissipation	P _{Max}		50		mW	

Steinhart & Hart Coefficients for NTC Resistance & NTC Temperature Computation (T in K)

$$\ln\left(\frac{R}{R_{25}}\right) = A + \frac{B}{T} + \frac{C}{T^2} + \frac{D}{T^3}$$

-1.289E+01 4.245E+03 -8.749E+04 -9.588E+06

$$\ln\left(\frac{R}{R_{25}}\right) = A + \frac{B}{T} + \frac{C}{T^2} + \frac{D}{T^3}$$

$$\frac{1}{T} = A_1 + B_1 \ln\left(\frac{R}{R_{25}}\right) + C_1 \ln^2\left(\frac{R}{R_{25}}\right) + D_1 \ln^3\left(\frac{R}{R_{25}}\right)$$

 D_1 3.354E-03 3.001E-04 5.085E-06 2.188E-07

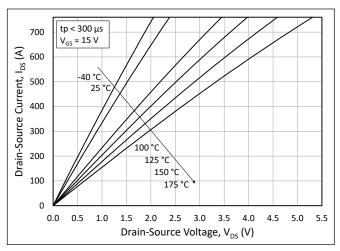


Figure 1. Output Characteristics for Various Junction Temperatures

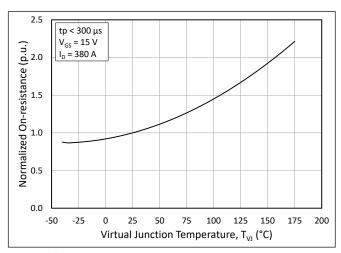


Figure 3. Normalized On-State Resistance vs. Junction Temperature

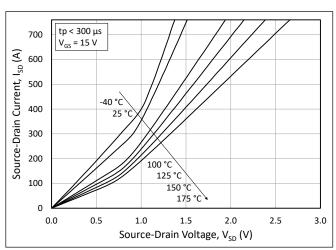


Figure 5. 3^{rd} Quadrant Characteristic vs. Junction Temperatures at $V_{GS} = 15 \text{ V}$

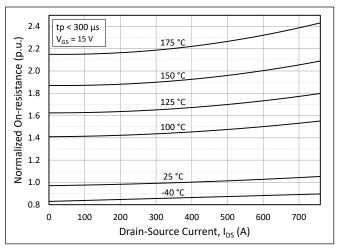


Figure 2. Normalized On-State Resistance vs. Drain Current for Various Junction Temperatures

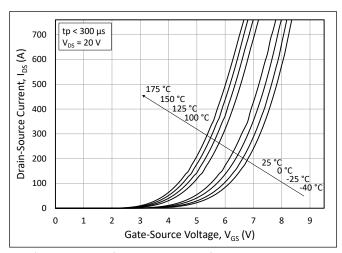


Figure 4. Transfer Characteristic for Various Junction Temperatures

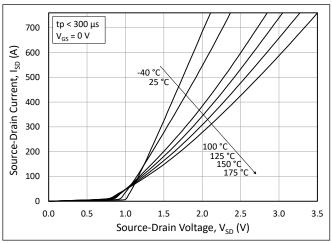


Figure 6. 3^{rd} Quadrant Characteristic vs. Junction Temperatures at $V_{GS} = 0 \text{ V}$

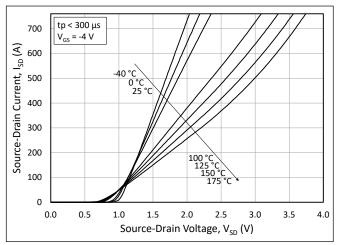


Figure 7. 3^{rd} Quadrant Characteristic vs. Junction Temperatures at $V_{GS} = -4 \text{ V}$

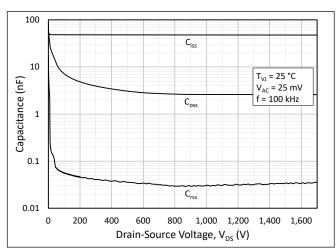


Figure 9. Typical Capacitances vs. Drain to Source Voltage (0 - 1200 V)

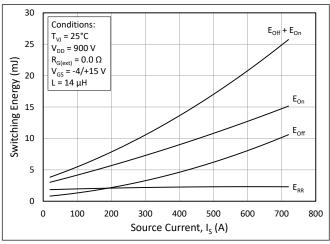


Figure 11. Switching Energy vs. Drain Current ($V_{DD} = 900 \text{ V}$)

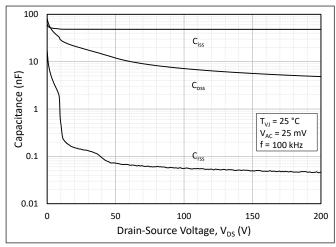


Figure 8. Typical Capacitances vs. Drain to Source Voltage (0 - 200 V)

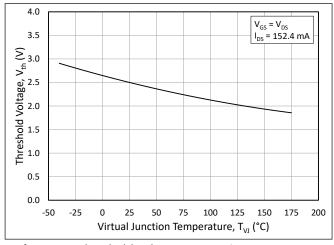


Figure 10. Threshold Voltage vs. Junction Temperature

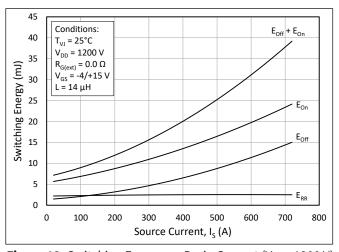


Figure 12. Switching Energy vs. Drain Current (V_{DD} = 1200 V)

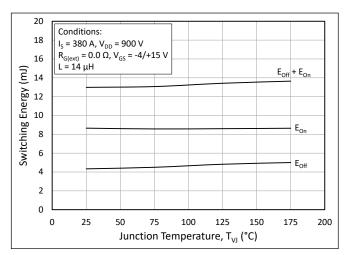


Figure 13. MOSFET Switching Energy vs. Junction Temperature

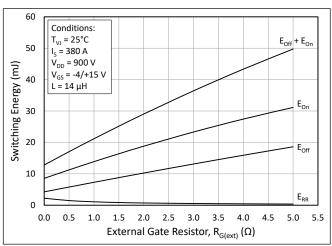


Figure 15. MOSFET Switching Energy vs. External Gate Resistance

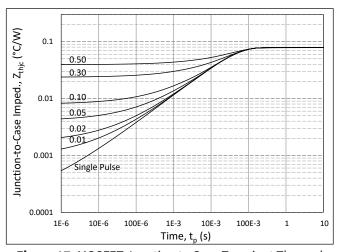


Figure 17. MOSFET Junction to Case Transient Thermal Impedance, $Z_{th,JC}$ (°C/W)

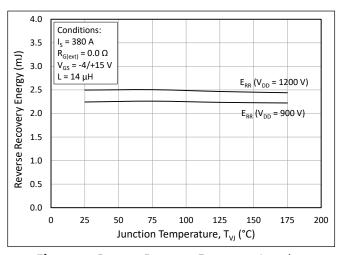


Figure 14. Reverse Recovery Energy vs. Junction Temperature

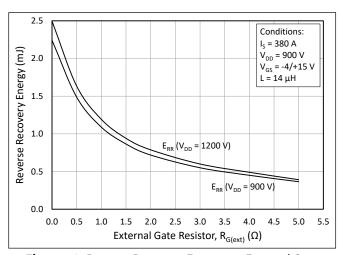


Figure 16. Reverse Recovery Energy vs. External Gate Resistance

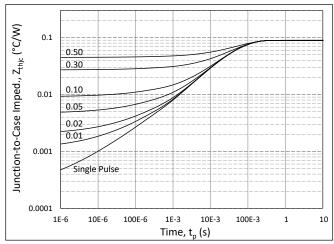


Figure 18. Diode Junction to Case Transient Thermal Impedance, $Z_{th JC}$ (°C/W)

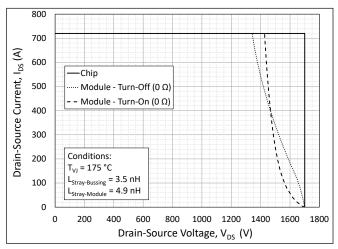


Figure 19. Reverse Bias Safe Operating Area (RBSOA)

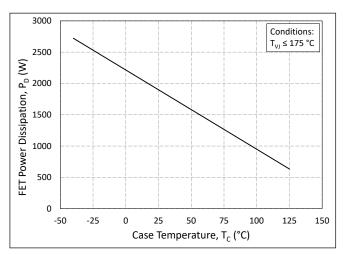


Figure 21. Maximum Power Dissipation Derating vs. Case Temperature

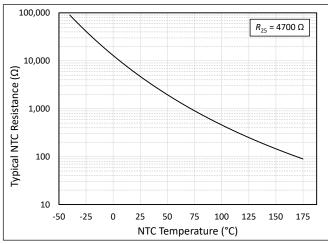


Figure 23. NTC Resistance vs. NTC Temperature

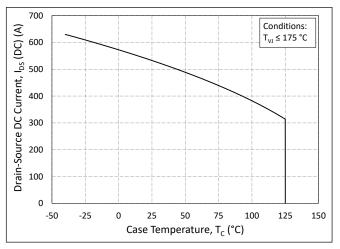


Figure 20. Continuous Drain Current Derating vs. Case Temperature

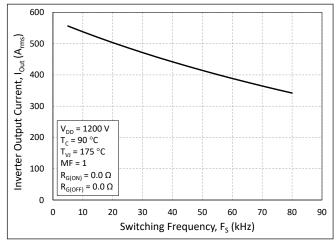


Figure 22. Typical Output Current Capability vs. Switching Frequency (Inverter Application)

Timing Characteristics

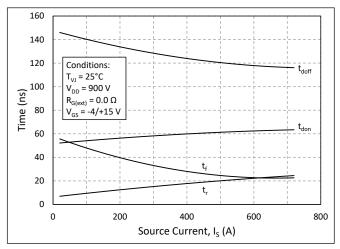


Figure 24. Timing vs. Source Current

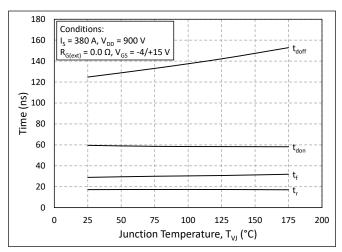


Figure 26. Timing vs. Junction Temperature

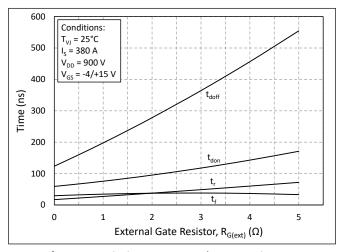


Figure 28. Timing vs. External Gate Resistance

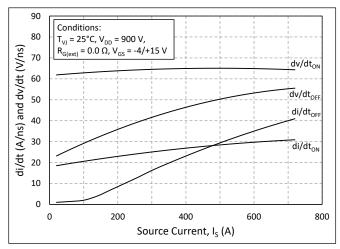


Figure 25. dv/dt and di/dt vs. Source Current

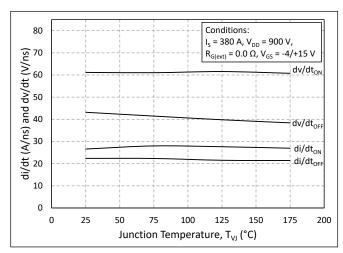


Figure 27. dv/dt and di/dt vs. Junction Temperature

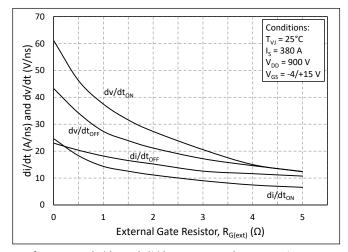


Figure 29. dv/dt and di/dt vs. External Gate Resistance

Definitions

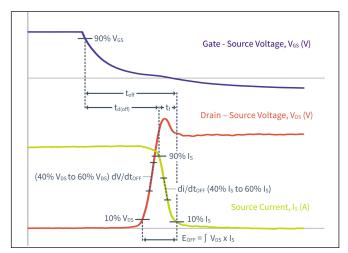


Figure 30. Turn-Off Transient Definitions

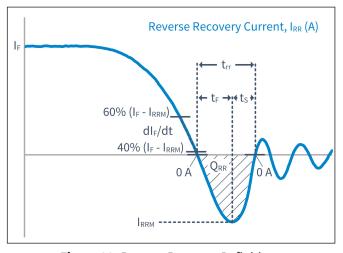


Figure 32. Reverse Recovery Definitions

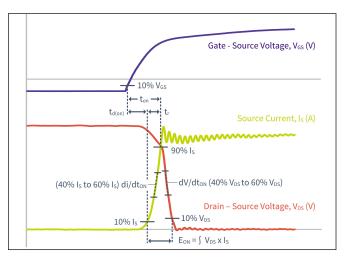


Figure 31. Turn-On Transient Definitions

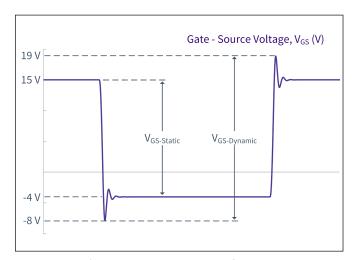
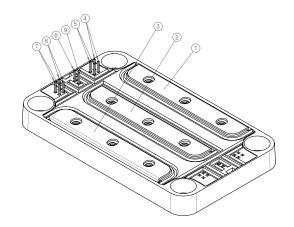
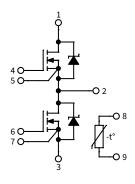


Figure 33. $V_{\rm GS}$ Transient Definitions

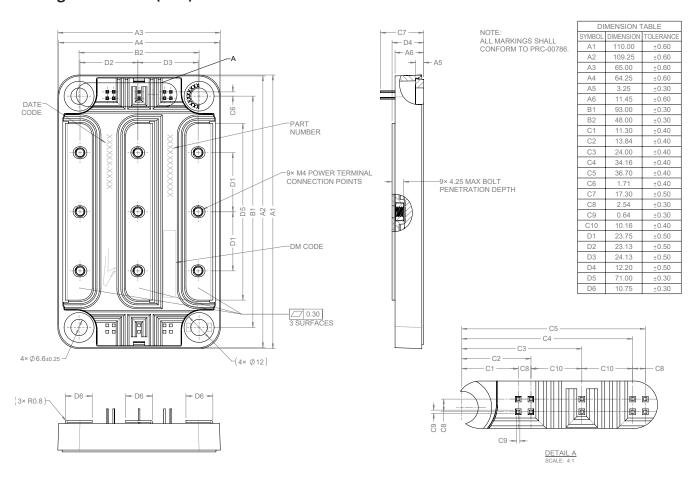
Schematic and Pin Out



PIN OUT SCHEME							
PIN	LABEL						
1	V+						
2	Mid						
3	V-						
4	G1, Top row pins (2)						
(5)	K1, Bottom row pins (2)						
6	G2, Top row pins (2)						
7	K2, Bottom row pins (2)						
8	NTC1						
9	NTC2						



Package Dimension (mm)



Supporting Links & Tools

Evaluation Tools & Support

- SpeedFit 2.0 Design Simulator™
- <u>Technical Support Forum</u>
- Dynamic Characterization Evaluation Tool for the High Performance 62mm (HM) Module Platform

Dual-Channel Gate Driver Board

- CGD1700HB3P-HM3: Wolfspeed Gate Driver Board
- CGD12HB00D: Differential Transceiver Daughter Board Companion Tool for Differential Gate Drivers

Application Notes

- CPWR-AN35: 62mm Thermal Interface Material Application Note
- CPWR-AN39: KIT-CRD-CIL12N-HM User Guide
- PRD-04814: Design Options for Wolfspeed® Silicon Carbide MOSFET Gate Bias Power Supplies

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